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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): Kazutaka Shibata and Tsunemori Yamaguchi

Serial No.: 09/204,123

Filed: December 2, 1998

For: METHOD OF SURFACE-MOUNTING ELECTRONIC COMPONENTS

Group Art Unit: 3729

Examiner: S. Smith

Attorney Docket: 8046.037US0  
0800241.0042)

**CERTIFICATE OF MAILING/TRANSMISSION  
(37 C.F.R. § 1.8(a))**

I hereby certify that this correspondence is, on the date shown below, being:

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June 21, 2001  
Date

*Diana R. Castillo*  
Diana R. Castillo

**AMENDMENT "D"**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action in the above-referenced application dated February 22, 2001, regarding which it is hereby requested with the payment of a fee that the period for responding to the aforementioned Office Action be extended by one month to June 22, 2001, applicant amends the application as follows:

**IN THE CLAIMS:**

Amend claim 1 as follows:

1. (Twice amended) A method of surface-mounting a plurality of electronic components having conductive connecting members, said method comprising the steps of:  
providing a target surface having a plurality of specified terminal-forming areas thereon,

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